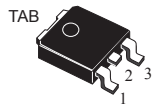
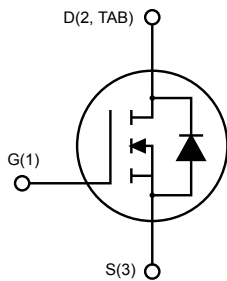


## Automotive-grade N-channel 60 V, 0.07 $\Omega$ typ., 12 A STripFET II Power MOSFET in a DPAK package




DPAK



AM01475v1\_noZen

### Features

Order code	$V_{DS}$	$R_{DS(on)}$ max.	$I_D$
STD12NF06LAG	60 V	0.09 m $\Omega$	12 A

- AEC-Q101 qualified 
- Exceptional dv/dt capability
- 100% avalanche tested
- Low gate charge

### Applications

- Switching applications

### Description

This Power MOSFET has been developed using STMicroelectronics' unique STripFET process, which is specifically designed to minimize input capacitance and gate charge. This renders the device suitable for use as primary switch in advanced high-efficiency isolated DC-DC converters for telecom and computer applications, and applications with low gate charge driving requirements.



#### Product status link

[STD12NF06LAG](#)

#### Product summary

<b>Order code</b>	STD12NF06LAG
<b>Marking</b>	D12NF06L
<b>Package</b>	DPAK
<b>Packing</b>	Tape and reel

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	60	V
$V_{GS}$	Gate-source voltage	$\pm 16$	V
$I_D$	Drain current (continuous) at $T_{case} = 25\text{ }^\circ\text{C}$	12	A
	Drain current (continuous) at $T_{case} = 100\text{ }^\circ\text{C}$	8.5	
$I_{DM}^{(1)}$	Drain current (pulsed)	48	A
$P_{TOT}$	Total dissipation at $T_{case} = 25\text{ }^\circ\text{C}$	30	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	15	V/ns
$E_{AS}^{(3)}$	Single pulse avalanche energy	100	mJ
$T_{stg}$	Storage temperature range	-55 to 175	$^\circ\text{C}$
$T_J$	Operating junction temperature range		

1. Pulse width is limited by safe operating area.
2.  $I_{SD} \leq 12\text{ A}$ ,  $di/dt \leq 200\text{ A}/\mu\text{s}$ ,  $V_{DS} \leq 40\text{ V}$ ,  $T_J \leq T_{JMAX}$
3. Starting  $T_J = 25\text{ }^\circ\text{C}$ ,  $I_D = 6\text{ A}$ ,  $V_{DD} = 30\text{ V}$

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	5	$^\circ\text{C}/\text{W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	50	

1. When mounted on a 1-inch<sup>2</sup> FR-4, 2 Oz copper board.

## 2 Electrical characteristics

( $T_{case} = 25\text{ °C}$  unless otherwise specified)

**Table 3. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	60			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{ V}, V_{DS} = 60\text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0\text{ V}, V_{DS} = 60\text{ V}, T_{case} = 125\text{ °C}^{(1)}$			10	
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0\text{ V}, V_{GS} = \pm 16\text{ V}$			$\pm 100$	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	1		2	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}, I_D = 6\text{ A}$		70	90	m $\Omega$
		$V_{GS} = 5\text{ V}, I_D = 6\text{ A}$		80	100	

1. Defined by design, not subject to production test.

**Table 4. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}, V_{GS} = 0\text{ V}$	-	350		$\mu\text{F}$
$C_{oss}$	Output capacitance		-	75		
$C_{riss}$	Reverse transfer capacitance		-	30		
$Q_g$	Total gate charge	$V_{DD} = 48\text{ V}, I_D = 12\text{ A},$	-	7.5	10	nC
$Q_{gs}$	Gate-source charge	$V_{GS} = 0\text{ to }5\text{ V}$	-	2.5		
$Q_{gd}$	Gate-drain charge	(see Figure 13. Test circuit for gate charge behavior)	-	3.0		

**Table 5. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 30\text{ V}, I_D = 6\text{ A},$	-	10	-	ns
$t_r$	Rise time	$R_G = 4.7\text{ }\Omega, V_{GS} = 4.5\text{ V}$	-	35	-	
$t_{d(off)}$	Turn-off delay time	(see Figure 12. Test circuit for resistive load switching times and Figure 17. Switching time waveform)	-	20	-	
$t_f$	Fall time		-	13	-	

**Table 6. Source-drain diode**

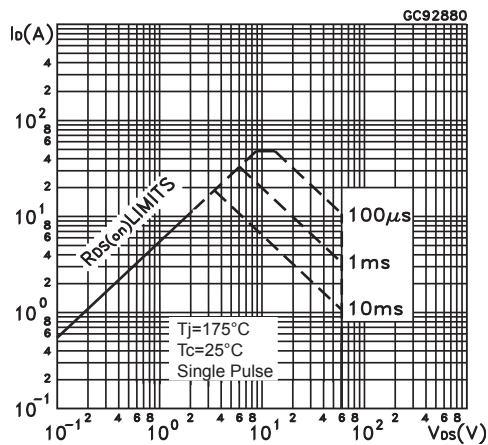
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		12	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		48	A

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0\text{ V}$ , $I_{SD} = 12\text{ A}$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 12\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ ,	-	50		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 16\text{ V}$ , $T_J = 150\text{ }^\circ\text{C}$	-	65		nC
$I_{RRM}$	Reverse recovery current	(see Figure 14. Test circuit for inductive load switching and diode recovery times)	-	2.5		A

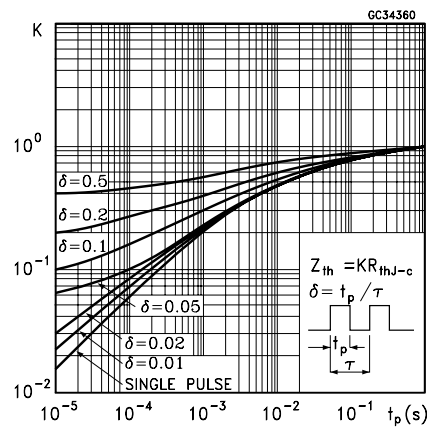
1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

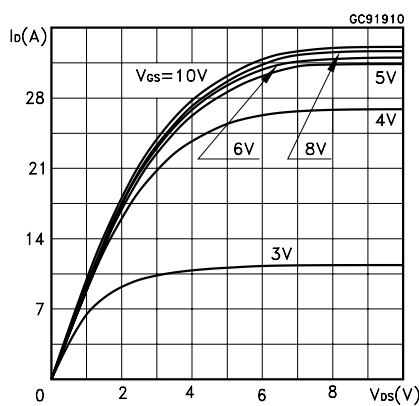
**Figure 1. Safe operating area**



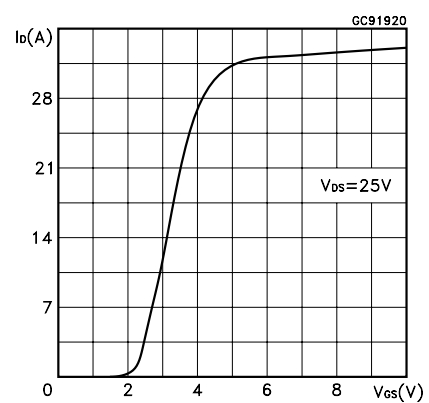
**Figure 2. Thermal impedance**



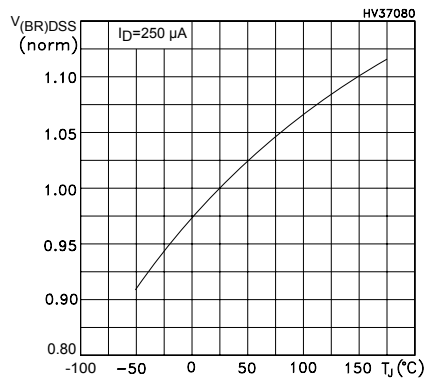
**Figure 3. Output characteristics**



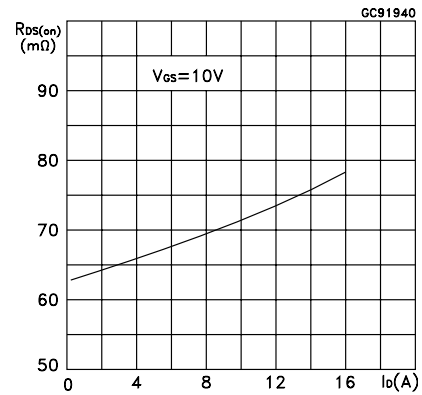
**Figure 4. Transfer characteristics**



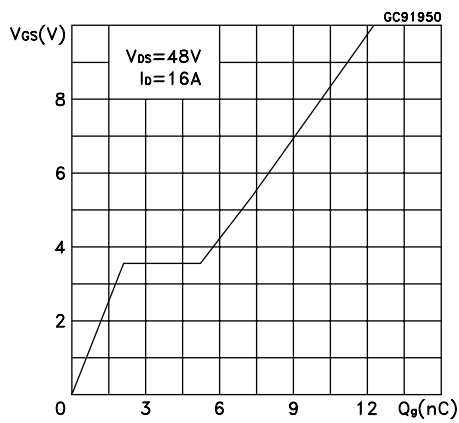
**Figure 5. Normalized  $V_{(BR)DSS}$  vs temperature**



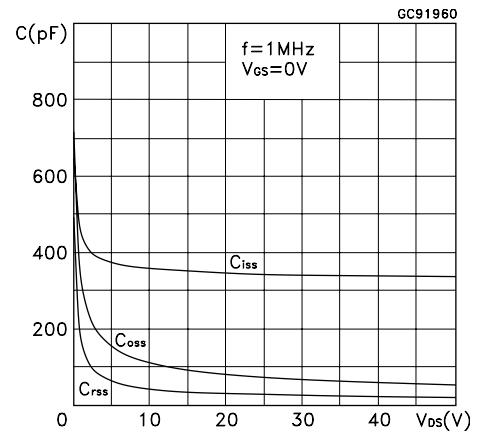
**Figure 6. Static drain-source on-resistance**



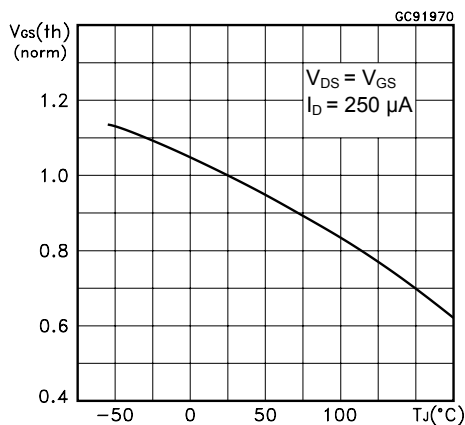
**Figure 7. Gate charge vs gate-source voltage**



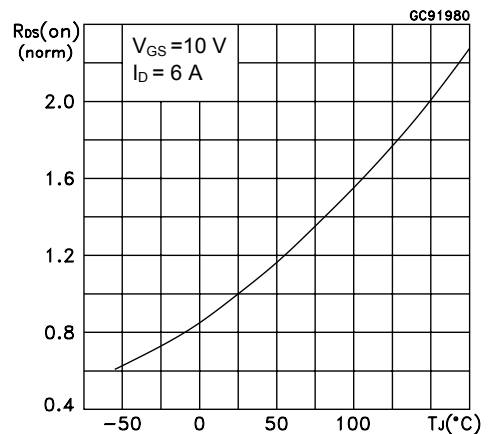
**Figure 8. Capacitance variations**



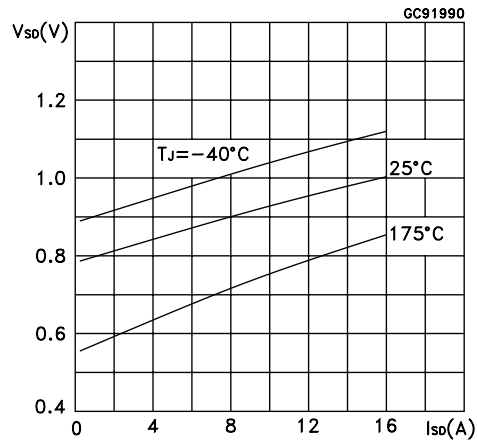
**Figure 9. Normalized gate threshold vs temperature**



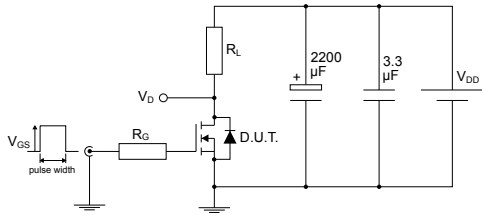
**Figure 10. Normalized on-resistance vs temperature**



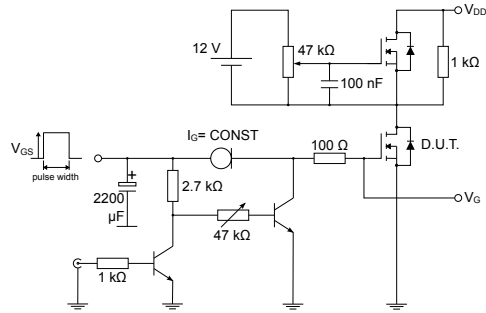
**Figure 11. Source-drain diode forward characteristics**



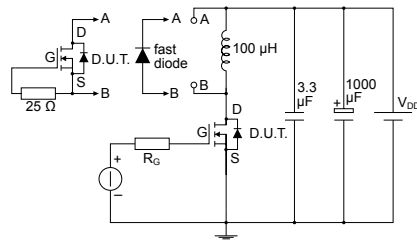
### 3 Test circuits

**Figure 12. Test circuit for resistive load switching times**


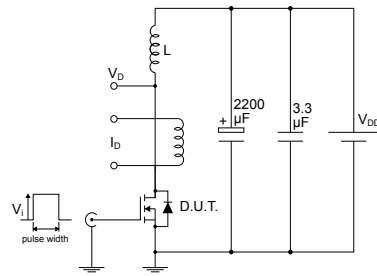
AM01468v1

**Figure 13. Test circuit for gate charge behavior**


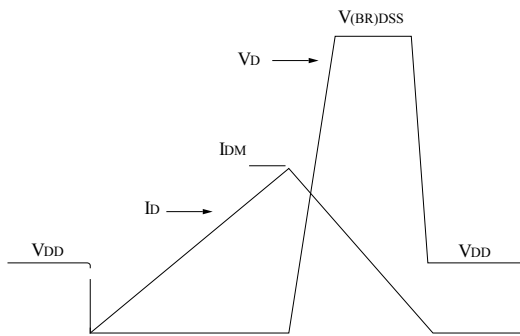
AM01469v1

**Figure 14. Test circuit for inductive load switching and diode recovery times**


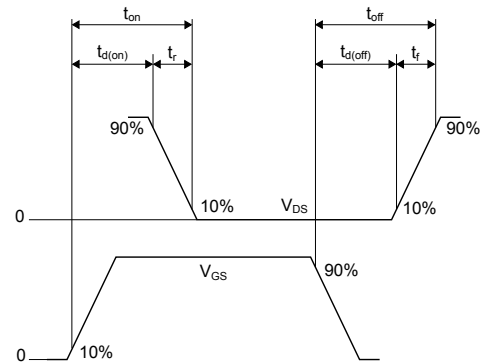
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**Figure 15. Unclamped inductive load test circuit**


AM01471v1

**Figure 16. Unclamped inductive waveform**


AM01472v1

**Figure 17. Switching time waveform**


AM01473v1

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## 4 Package information

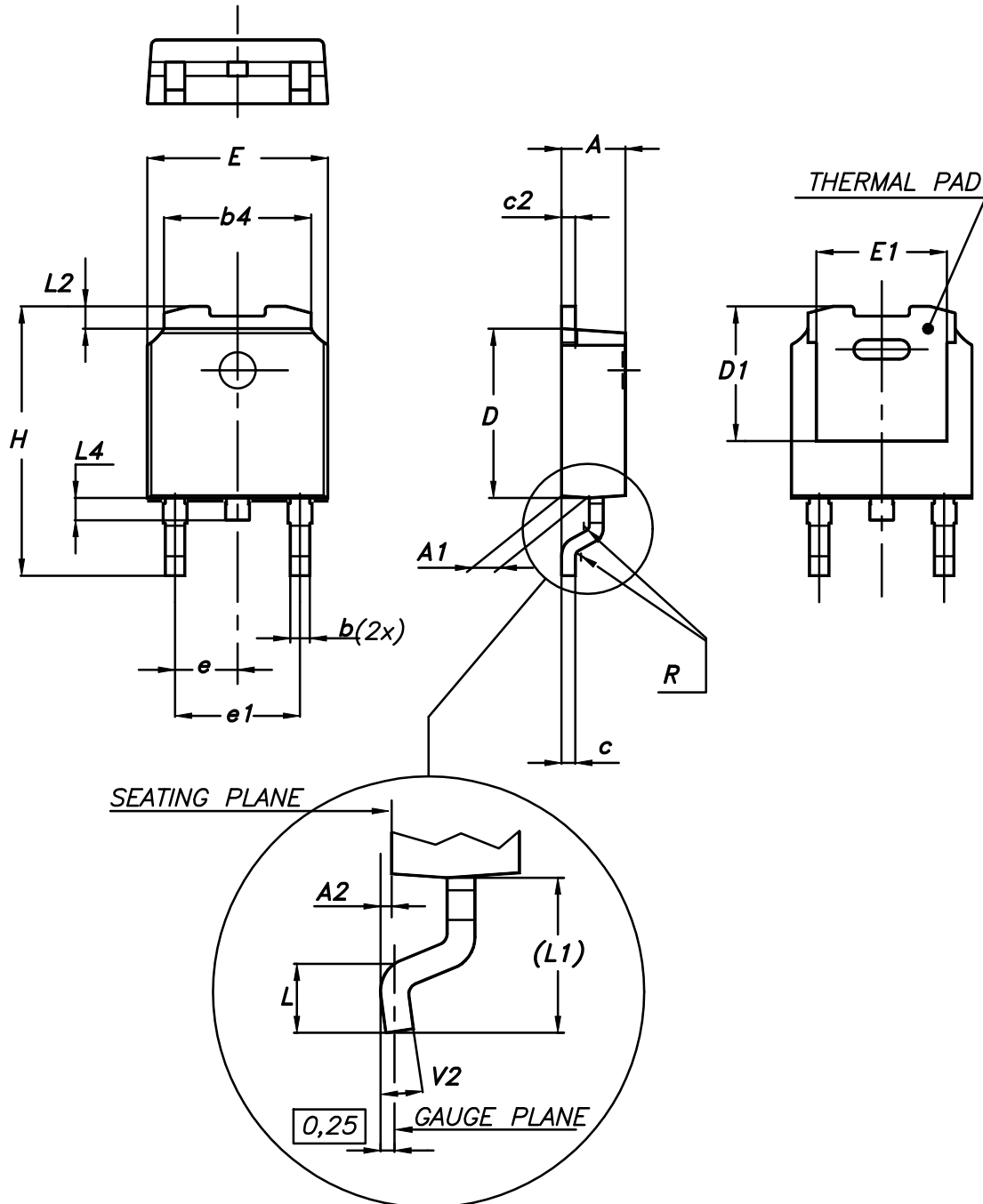
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In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.



### 4.1 DPAK (TO-252) type A package information

Figure 18. DPAK (TO-252) type A package outline

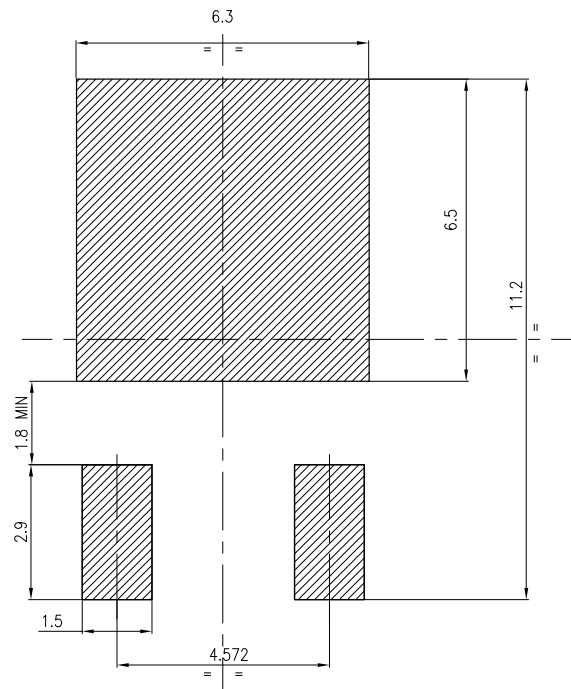


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**Table 7. DPAK (TO-252) type A mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

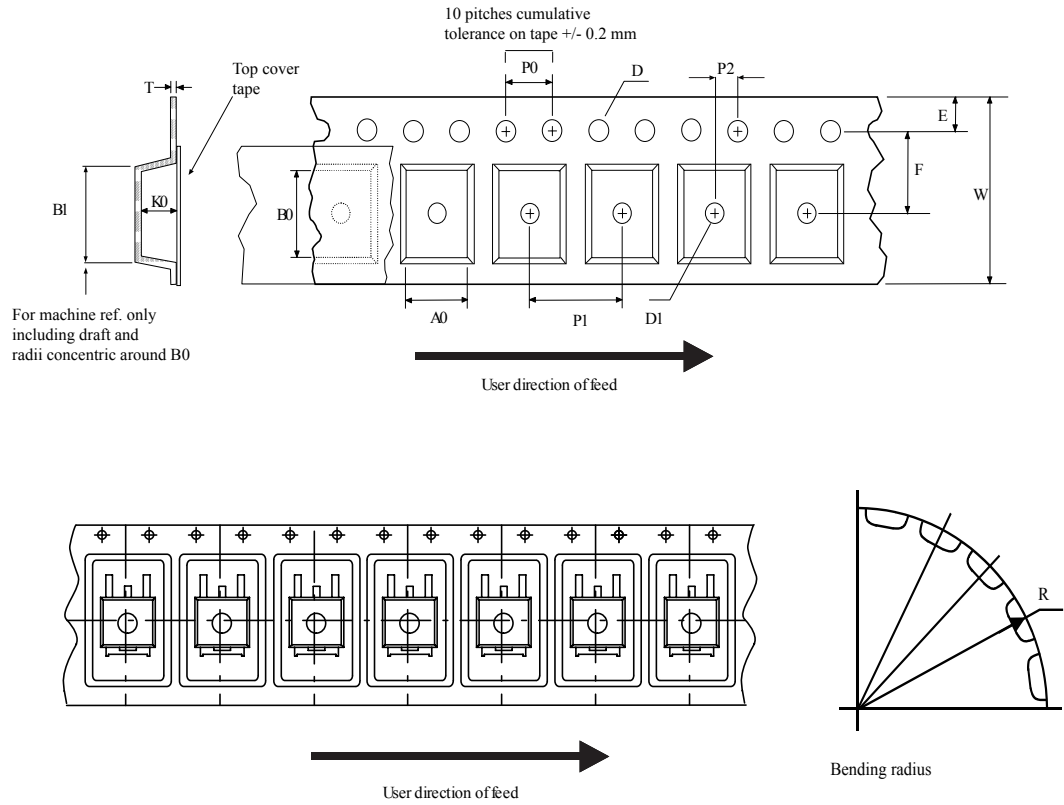
**Figure 19. DPAK (TO-252) type A recommended footprint (dimensions are in mm)**



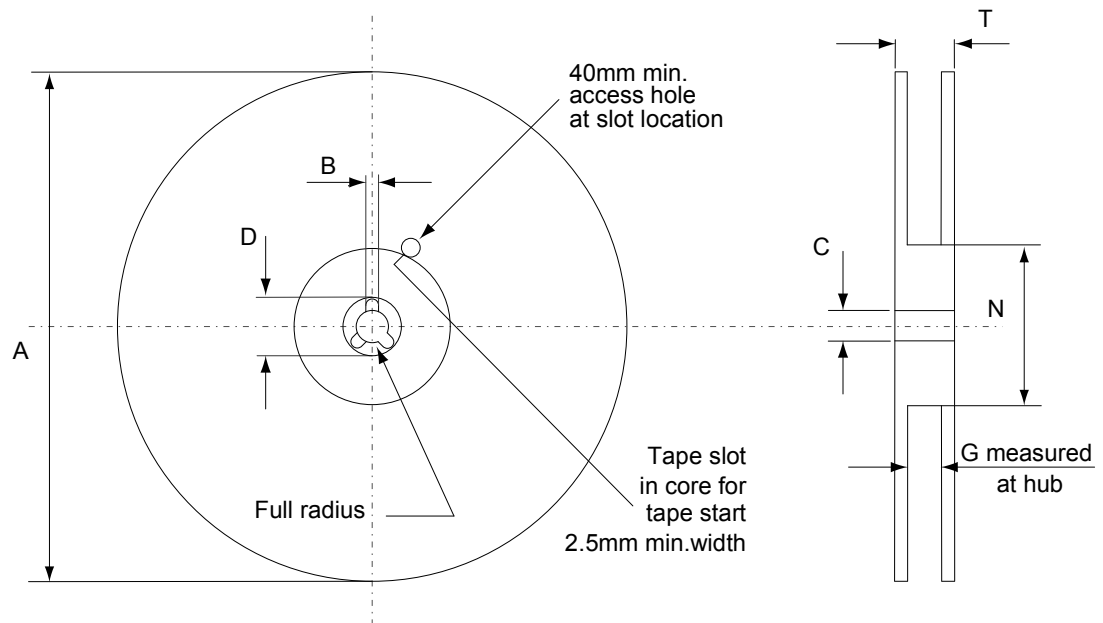
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## 4.2 DPAK (TO-252) packing information

Figure 20. DPAK (TO-252) tape outline



AM08852v1

**Figure 21. DPAK (TO-252) reel outline**


AM06038v1

**Table 8. DPAK (TO-252) tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1		Base qty.	2500
P1	7.9	8.1		Bulk qty.	2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

## Revision history

**Table 9. Document revision history**

Date	Revision	Changes
15-Feb-2017	1	First release
10- Jun-2019	2	New template. Minor changes.

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